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Of Counsel
Lewis T. Steadman

November 15, 2006

Mr. Curt Dundas
3821 Simms Avenue
Albuquerque, NM 87108

Re: SELECTIVE TREATMENT OF MICROELECTRONIC
WORKPIECE SURFACES
Serial No. 10/647,914
Semitool Reference: P00-0024US3
Our Reference: 114183-20

Dear Mr. Dundas:

We are working with Pete Cross at Semitool in connection with an application pending in the United States Patent Office in which you were named as a co-inventor. For your information, I am enclosing a copy of that application and the claims as they currently stand to refresh your recollection as to the subject matter of this application.

We have filed this patent application and claims to provoke an interference with a patent owned by a third party which discloses and claims the same subject matter. We have determined that some of the work falling within the scope of the present application was done by one of your colleagues, namely Steven D. Peace, and have concluded that our position in the interference would be improved by adding Mr. Peace as an inventor.

That requires the consent of the named inventors as well as the consent of Semitool, which I have already secured.

I am enclosing, for your information, a copy of a Declaration Under 37 C.F.R. §§ 1.48 And 1.131 for Mr. Peace to sign explaining his role as a co-inventor. I am also enclosing, for your information, our Request to add him as an inventor as well as our Supplemental Response that explains the significance of his work on the prospective interference.

EXHIBIT

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If you are in agreement with our course of action, I would ask that you sign the Replacement Declaration and Power of Attorney which is enclosed and return it to me in the self-addressed envelope. Your name will remain as a co-inventor on any patent that issues. Needless to say, if you have any questions regarding any of the foregoing, please do not hesitate to let me know, either by phone or email. My email address is krockey@rdklaw.com.

Very truly yours,

Keith V. Rockey

KVR/emmm
Enclosures

cc: Harry M. Cross Jr., Esq.

Jayne Schwartz

From: TrackingUpdates@fedex.com
Sent: Friday, November 17, 2006 3:43 PM
To: Jayne Schwartz
Subject: FedEx Shipment 798544733940 Delivered

This tracking update has been requested by:

Company Name: Rockey, Depke, Lyons & Kitzing

Name: Kathleen Lyons

E-mail: jschwartz@rdlklaw.com

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Tracking number:	798544733940
Reference:	114183-20
Ship (P/U) date:	Nov 17, 2006
Delivery date:	Nov 17, 2006 14:36 PM
Sign for by:	Signature Release on file
Delivered to:	Residence
Service type:	FedEx Standard Overnight
Packaging type:	FedEx Pak
Number of pieces:	1
Weight:	2.0 LB

Shipper Information
Kathleen Lyons
Rockey, Depke, Lyons & Kitzing
233 S. Wacker Drive
54th Floor
Chicago
IL
US
60606

Recipient Information
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1/6/2007

Thank you for your business.

1/6/2007

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Brian Aegerter, et al.

Application No.: 10/647,914

Conf. No.: 2441

Filed On: August 26, 2003

For: SELECTIVE TREATMENT OF MICROELECTRONIC
WORKPIECE SURFACES

Art Unit: 1746

Examiner: Michail Kornakov

Docket No.: 114183-20 (P00-0024US3)

DECLARATION UNDER
37 C.F.R. §§ 1.48 AND 1.131 OF STEVEN L. PEACE

I, Steven L. Peace, hereby declare and say that:

1. I am an engineer residing in Whitefish, Montana and presently serve as a consultant to Semitool, Inc., the assignee of the above-identified application. Prior to the time that I became a consultant to Semitool, I was a research engineer employed by Semitool. During the time that I was employed by Semitool, I worked with Gary L. Curtis, one of the named inventors in the above-identified application.

2. I have reviewed the specification and the claims currently pending in the above-identified application. I am informed by counsel for

Application No. 10/647,914
Declaration Under 37 C.F.R. §§ 1.48
and 1.131 of Steven L. Peace
September 11, 2006

Semitool that the claims which have been presented in the above-identified application were copied from U.S. Patent No. 6,290,865, which issued September 18, 2001 to Applied Materials, Inc. Those claims are directed to a method of removing a film of a deposited metal material in which a substrate such as a silicon wafer has a film of a deposited metal material on at least one surface which is unwanted. The substrate is rotated while a rinse or inert fluid is supplied to one surface to substantially prevent removal of the film from that surface while a dissolving or etching solution is directed to another surface to remove the unwanted metal material from that surface.

3. Having reviewed those claims, I verily believe that I conceived and reduced to practice subject matter falling within the claims as presented in the present application prior to November 30, 1998. To demonstrate such conception and reduction to practice, I attach hereto as Exhibit A an Invention Disclosure which I prepared and signed (and which was witnessed by Gary Curtis and Coby Grove) disclosing a single-sided etch process as disclosed and claimed in the present application. Exhibit A was prepared by me prior to November 30, 1998 and lists dates of conception, first sketch or drawing and date of first written description, all prior to November 30, 1998. In addition, Exhibit A shows that a working model was prepared prior to November 30, 1998.

4. While working at Semitool as a research engineer, Mr. Curtis and I worked on techniques by which wafers could be etched selectively, with an etchant being applied to one side of the wafer and an inert fluid applied to the other. In those techniques, the inert fluid protected any coatings on that side of the wafer while the etchant removed any coatings on the other side of the wafer.

5. The selective etching process I conceived and reduced to practice is described in Exhibit A which includes a sketch at the top of the second page. That sketch depicts a wafer which is contacted on its upper side with nitrogen gas or N_2 , while an etchant, referred to as "Chem", is supplied to the other side of the wafer. The chemicals used in the etching process are described on the first page of Exhibit A, referring to hydrogen fluoride etch of oxide layers and nitric acid etch of copper layers. Thus, in the etching process described in Exhibit A, I supplied liquid nitric acid as the "Chem" agent and nitrogen gas as the inert fluid. The nitric acid flowed along the underside of the wafer illustrated in the sketch and effected removal of metallic copper from the wafer surface. Simultaneously, nitrogen gas flowed alongside the upper surface of the wafer as illustrated in the sketch and protected that upper surface from the actions of the nitric acid, as described and claimed in the present application.

6. Thus, the claims presently in the application are directed specifically to methods that I conceived and reduced to practice. I therefore verily believe that I am a co-inventor of the subject matter of the present application and the claims set forth therein. Because such subject matter was not claimed originally, I was not included in the application as originally filed as a co-inventor. I believe that I should be added as a co-inventor in light of the present claims. I verily believe that I was omitted as an inventor by reason of a change in the claims. Therefore, it is my belief that the failure to include me as an inventor in the application as originally filed was entirely without deceptive intent.

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and 1.131 of Steven L. Peace
September 11, 2006

7. I hereby declare under penalty of perjury under the laws of the United States of America that the foregoing is true and correct to the best of my knowledge and belief.

8. Further declarant sayeth not.

Executed this ____ day of August, 2006 in Kalispell, Montana.

9/29/06 Steven L. Peace
Steven L. Peace